

ABSTRACT OF THE DISCLOSURE

Attaining improvement of the reliability and standardization of the lead frame.

A semiconductor device comprises a plurality of inner leads extending around a semiconductor chip, a tape substrate 5 supporting the semiconductor chip and joined to respective end portions of the inner leads, wires connecting the inner leads and pads formed on a main surface of the semiconductor chip, a seal portion formed by resin-sealing the semiconductor chip and the wires, and a plurality of outer leads linking in a line with the inner leads and protruded from the seal portion to the exterior of four directions. A relationship between a length (a) of a shorter side of the semiconductor chip and a clearance (b) from the semiconductor chip, to a tip of the inner leads arranged at the farthest location from the semiconductor chip is $a \geq 2b$. It is possible to attain a narrow pad pitch, and mount the semiconductor chip formed in a small size, and standardize the lead frame.